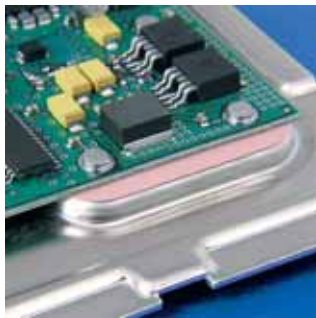


Sil-Pad® Thermally Conductive

	Sil-Pad 400 .007 in.	Sil-Pad 400 .009 in.	Sil-Pad 800	Sil-Pad 900S	Sil-Pad 980	Sil-Pad 1100ST	Sil-Pad 1200	Sil-Pad A1500
Color	Gray	Gray	Gold	Pink	Mauve	Yellow	Black	Green
Thickness (in/mm)	.007 ± .001 (.18 ± .025)	.009 ± .001 (.23 ± .025)	.005 ± .001 (.13 ± .025)	.009 ± .001 (.23 ± .025)	.009 ± .001 (.23 ± .025)	.012 ± .001 (.30 ± .025)	.009 ± .001 (.23 ± .025)	.010 ± .001 (.25 ± .025)
Thermal Performance TO-220 Test @ 50 psi °C/W	5.14	6.61	2.45	2.50	4.52	2.68	2.41	2.21
Thermal Impedance (°C- in ² /W)	1.13	1.45	0.53	0.61	1.07	0.81	0.53	0.42
Thermal Conductivity (W/m-K nominal)	0.9	0.9	1.6	1.6	1.2	1.1	1.8	2.0
Voltage Breakdown (Vac)	3500	4500	2000	4500	4000	3000	6000	4000
Continuous Use Temperature (°C)	-60 to 180	-60 to 180	-60 to 180	-60 to 180	-40 to 150	-60 to 180	-60 to 180	-60 to 180
Construction	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass

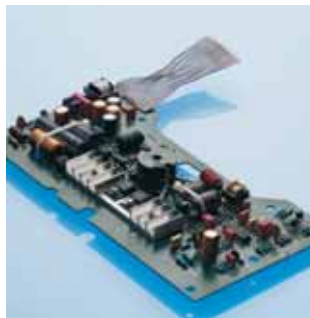
Sil-Pad Applications



Here, Sil-Pad 900S enhances the thermal transfer from this FR-4 circuit board with thermal vias to the metal base plate.



Sil-Pad is available in over 100 standard configurations for common JEDEC package outlines.



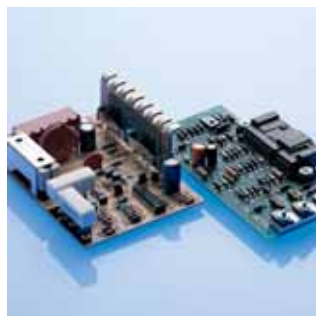
The circuit board above shows punched parts interfacing screw-mounted transistors to a finned heat sink.



This application uses Sil-Pad to isolate the mounting brackets from the assembly frame.



A common Sil-Pad application includes TO-220 transistors mounted in a row on a heat rail.



These Sil-Pad applications show clip mounting of transistors on the left and screw mounting to an aluminum bracket on the right.



Choose a Sil-Pad that optimizes thermal performance for your mounting method — screw, clip, spring, bar, etc.



Sil-Pad 980 is used extensively in industrial applications having excellent cut-through and abrasion resistance.

Insulator Selection Table

Sil-Pad 1500ST	Sil-Pad 2000	Sil-Pad A2000	Sil-Pad K-4	Sil-Pad K-6	Sil-Pad K-10	Poly-Pad 1000	Poly-Pad K-4	Poly-Pad K-10	Test Method
Blue	White	White	Gray	Bluegreen	Beige	Yellow	Tan	Yellow	Visual
.008 ± .001 (.20 ± .025)	.010 ± .001 (.25 ± .025)	.015 ± .001 (.38 ± .025)	.006 ± .001 (.15 ± .025)	.006 ± .001 (.15 ± .025)	.006 ± .001 (.15 ± .025)	.009 ± .001 (.23 ± .025)	.006 ± .001 (.15 ± .025)	.006 ± .001 (.15 ± .025)	ASTM D374
1.51	2.02	1.86	3.13	2.76	2.01	3.74	4.34	2.75	ASTM D5470
0.23	0.33	0.32	0.62	0.64	0.41	0.82	0.95	0.60	ASTM D5470
1.8	3.5	3.0	0.9	1.1	1.3	1.2	0.9	1.3	ASTM D5470
3000	4000	4000	6000	6000	6000	1300	5500	6000	ASTM D149
-60 to 180	-60 to 200	-60 to 200	-60 to 180	-60 to 180	-60 to 180	-20 to 150	-20 to 150	-20 to 150	—
Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Fiberglass	Silicone/ Film	Silicone/ Film	Silicone/ Film	Polyester/ Fiberglass	Polyester/ Film	Polyester/ Film	—

Sil-Pad Comparison Made Simple!



Comparing thermally conductive interface materials has never been easier.

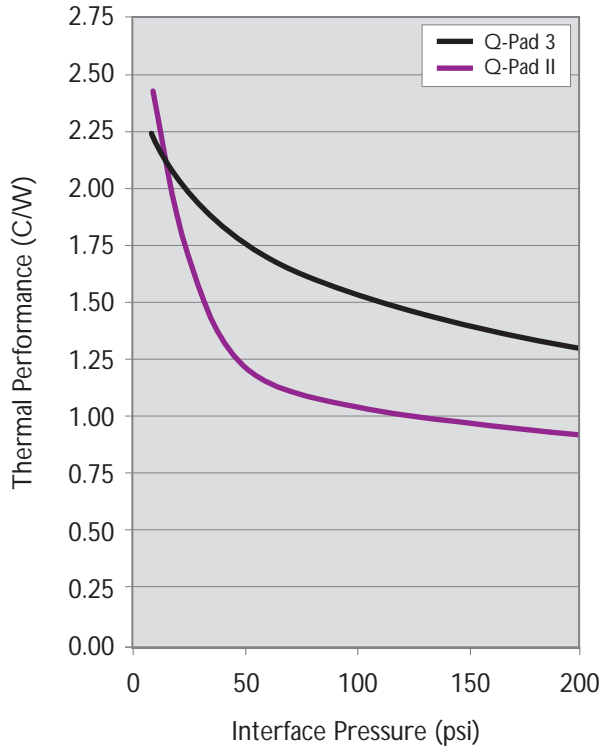
Simply go to the "Thermal Materials" section of the Bergquist website (www.bergquistcompany.com) and select "Compare Material Properties." Then select up to three separate products and this handy comparison tool will automatically chart thermal resistance values and display a material properties table of the selected materials.

The materials comparison tool can be used for most Bergquist thermal materials, including Sil-Pad, Hi-Flow, Gap Pad, Q-Pad, Bond-Ply and Liqui-Bond products.

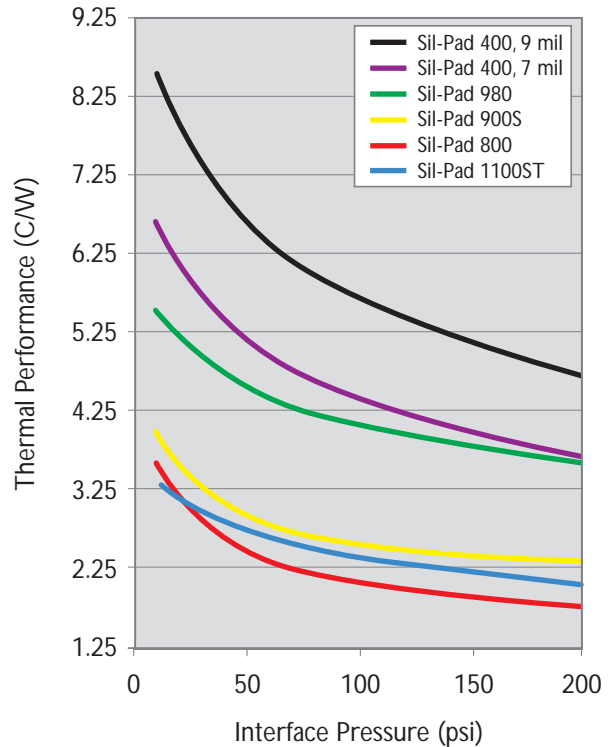
Sil-Pad® Comparison Data

TO-220 Thermal Performance

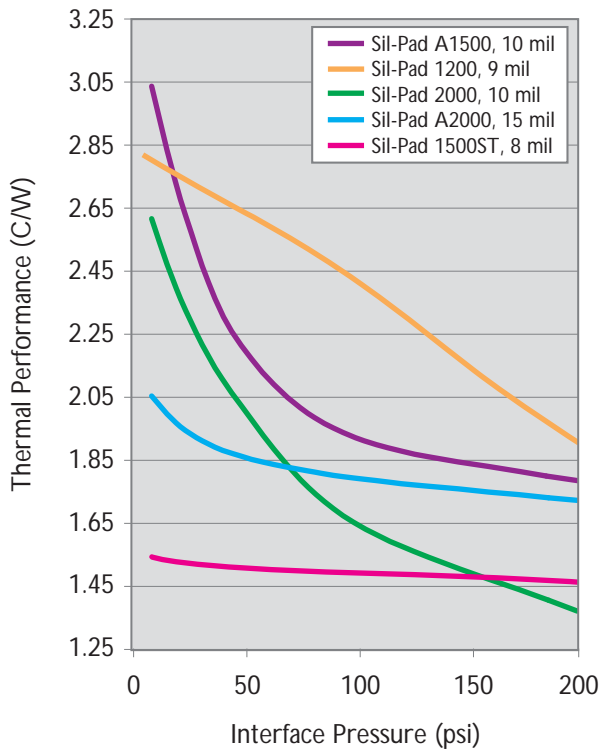
Q-Pad Materials
Non-Electrically Isolating



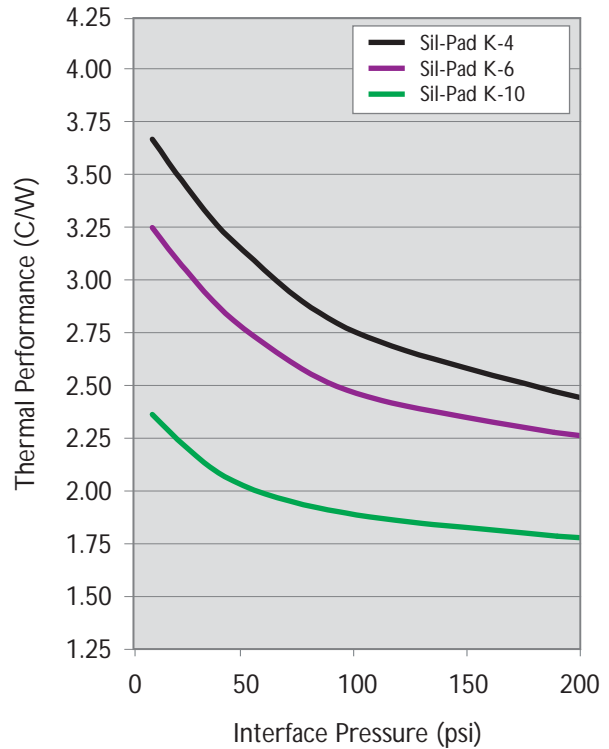
Sil-Pad High Value Materials



Sil-Pad High Performance Materials



Sil-Pad Polyimide-Based Materials



SIL-PAD